AP1115AY15G, AP1115AY18G, AP1115AY25G, AP1115AY28G, AP1115AY30G, AP1115AY33G, AP1115AY35G, AP1115AY50G, AP1115AYG,
AP1115BY15G, AP1115BY18G, AP1115BY25G, AP1115BY28G, AP1115BY30G, AP1115BY33G, AP1115BY35G, AP1115BY50G, AP1115BYG

Part Number: **Analog SOT89-3L See List above** p = package designator
Weight (mg): 54.95 See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	1.48	0.81	1000000	14767
Leadframe	CDA-194	Cu	7440-50-8	97.40%	44.35	24.37	974000	431991
		Fe	1309-37-1	2.40%			24000	10645
		P	7723-14-0	0.08%			800	355
		Zn	7440-66-6	0.12%			1200	532
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.57	0.31	1000000	5702
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.22	0.12	1000000	2177
Encapsulation	EME-G600	Epoxy Resin	------	5.00%	51.15	28.11	50000	25577
		Phenol Resin	------	5.00%			50000	25577
		Bismuth/Bismuth compound	------	1.00%			10000	5115
		SiO2	60676-86-0	86.50%			865000	442484
		Cresol Novolac	29690-82-2	2.00%			20000	10231
		C	1333-86-4	0.50%			5000	2558
Die Attach Epoxy	84-3J	Epoxy Resin	------	47.50%	0.27	0.15	475000	1291
		Silicon dioxide	------	45.00%			450000	1223
		curing agent & hardener	Trade secret	7.50%			75000	204
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.96	1.08	1000000	19573
				Total	100.00	54.95		1000000

Tolerance ±10%

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* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, _Material Composition Declaration for Electronic Products_.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS **and** reported above:

- Asbestos
- Azo compounds
- Cadmium and cadmium compounds
- Certain Shortchain Chlorinated Paraffins
- Chlorinated organic compounds
- Hexavalent chromium compounds
- Lead and lead compounds
- Mercury and mercury compounds
- Organic tin compounds
- Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
- Ozone Depleting Substances - Class II (HCFCs)
- Perfluorooctane Sulphonate (PFOS) or related compounds
- Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**
- Polychlorinated Biphenyls (PCBs)
- Polychlorinated Naphthalenes (> 3 chlorine atoms)
- Radioactive Substances
- Tributyl Tin (TBT) and Triphenyl Tin (TPT)
- Tributyl Tin Oxide (TBTO)

AP130-15YG-13, AP130-18YG-13, AP130-20YG-13, AP130-25YG-13, AP130-28YG-13, AP130-30YG-13, AP130-33YG-13, AP130-35YG-13,

Part Number: **Analog SOT89-3L See List above** p = package designator
Weight (mg): 55.84 See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	4.51	2.52	1000000	45854
Leadframe	CDA-194	Cu	7440-50-8	97.40%	43.64	24.37	974000	431991
		Fe	1309-37-1	2.40%			24000	10645
		P	7723-14-0	0.08%			800	355
		Zn	7440-66-6	0.12%			1200	532
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.56	0.31	1000000	5702
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.15	0.08	1000000	2177
Encapsulation	EME-G600	Epoxy Resin	------	5.00%	47.52	26.54	50000	25577
		Phenol Resin	------	5.00%			50000	25577
		Bismuth/Bismuth compound	------	1.00%			10000	5115
		SiO2	60676-86-0	86.50%			865000	442484
		Cresol Novolac	29690-82-2	2.00%			20000	10231
		C	1333-86-4	0.50%			5000	2558
Die Attach Epoxy	8200TI	Ag	7440-22-4	80.00%	1.69	0.94	800000	2174
		Acrylate resins	Trade secret	20.00%			200000	543
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.93	1.08	1000000	19260
				Total	100.00	55.84		1030775

Tolerance ±10%

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Asbestos
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

AP1117YG-13, AP1117Y15G-13, AP1117Y18G-13, AP1117Y25G-13, AP1117Y33G-13, AP1117Y50G-13

Part Number: **Analog SOT89-3L See List above** p = package designator
Weight (mg): 55.24 See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	1.47	0.81	1000000	14767
Leadframe	CDA-194	Cu	7440-50-8	97.40%	44.11	24.37	974000	431991
		Fe	1309-37-1	2.40%			24000	10645
		P	7723-14-0	0.08%			800	355
		Zn	7440-66-6	0.12%			1200	532
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.57	0.31	1000000	5702
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.34	0.19	1000000	2177
Encapsulation	EME-G600	Epoxy Resin	------	5.00%	50.87	28.10	50000	25577
		Phenol Resin	------	5.00%			50000	25577
		Bismuth/Bismuth compound	------	1.00%			10000	5115
		SiO2	60676-86-0	86.50%			865000	442484
		Cresol Novolac	29690-82-2	2.00%			20000	10231
		C	1333-86-4	0.50%			5000	2558
Die Attach Epoxy	8200TI	Ag	7440-22-4	80.00%	0.70	0.39	800000	2174
		Acrylate resins	Trade secret	20.00%			200000	543
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.95	1.08	1000000	19468
				Total	100.00	55.24		999895

Tolerance ±10%

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* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables o EIA JIG-101, *Material Composition Declaration for Electronic Products*.

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Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)